(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
20 April 2006 (20.04.2006)

PCT

(10) International Publication Number
WO 2006/042010 A1

(51) International Patent Classification:
*B24D 11/00* (2006.01)

(21) International Application Number:
PCT/US2005/035979

(22) International Filing Date: 5 October 2005 (05.10.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/616,944 6 October 2004 (06.10.2004) US
60/639,257 27 December 2004 (27.12.2004) US

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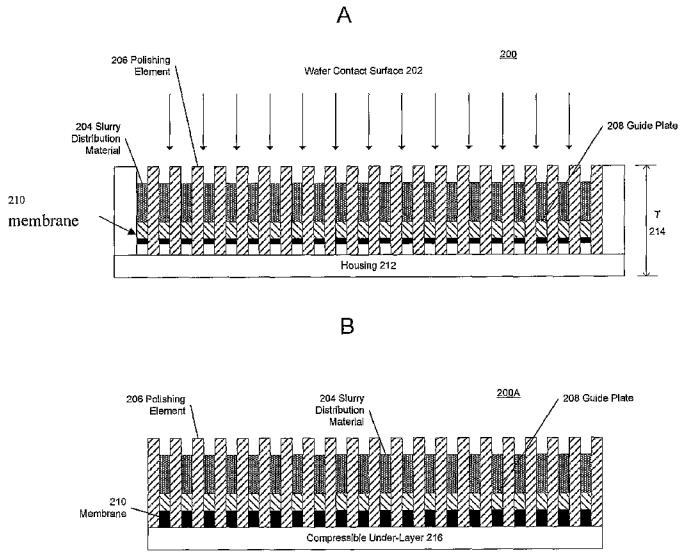
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION




(57) Abstract: A polishing pad includes a guide plate having affixed thereto a porous slurry distribution layer on one side and a flexible under-layer on the other side. A plurality of polishing elements interdigitated with one another through the slurry distribution layer and the guide plate so as to be maintained in planar orientation with respect to one other and the guide plate are affixed to the flexible under-layer and each polishing element protrudes above the surface of the guide plate to which the slurry distribution layer is adjacent. Optionally, a membrane may be positioned between the guide plate and the slurry distribution layer. The polishing pad may also include wear sensors to assist in determinations of pad wear and end-of-life.

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